



深圳瑞之辰科技有限公司

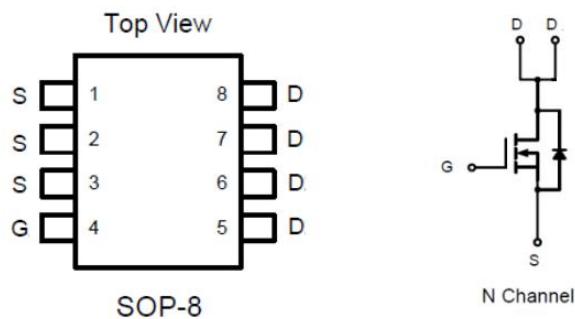
RZC3002

Dual Enhancement Mode MOSFET

## GENERAL DESCRIPTION

The RZC3002 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

## PIN CONFIGURATION



## FEATURES

- N-Channel  
30V/7A,  
 $R_{DS(ON)}=18m\Omega$  (MAX.) @  $V_{GS}=10V$   
 $R_{DS(ON)}=26m\Omega$  (MAX.) @  $V_{GS}=4.5V$
- Super High Dense Cell Design
- Reliable and Rugged

## APPLICATIONS

- Power Management in Notebook Computer
- Portable Equipment
- Battery Powered Systems

## ORDERING INFORMATION

Part Number	Package	Top Marking	Packing
RZC3002	SOP-8	S3002	3000PCS/Real



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## MAXIMUM RATINGS( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Units
Drain to Source Voltage	$V_{DSS}$	30	V
Gate to Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	25°C	A
		70°C	A
Pulsed Drain Current	$I_{D(\text{pulse})}$	35	A
Maximum Power Dissipation	$P_D(25^\circ\text{C})$	1.5	W
Single Pulse Avalanche Energy	$E_{AS}$	20	mJ
Operating Junction Temperature	$T_J$	+150	°C
Storage Temperature	$T_{STG}$	-55-+150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260	°C



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**ELECTRICAL CHARACTERISTICS (TA = 25°C)**

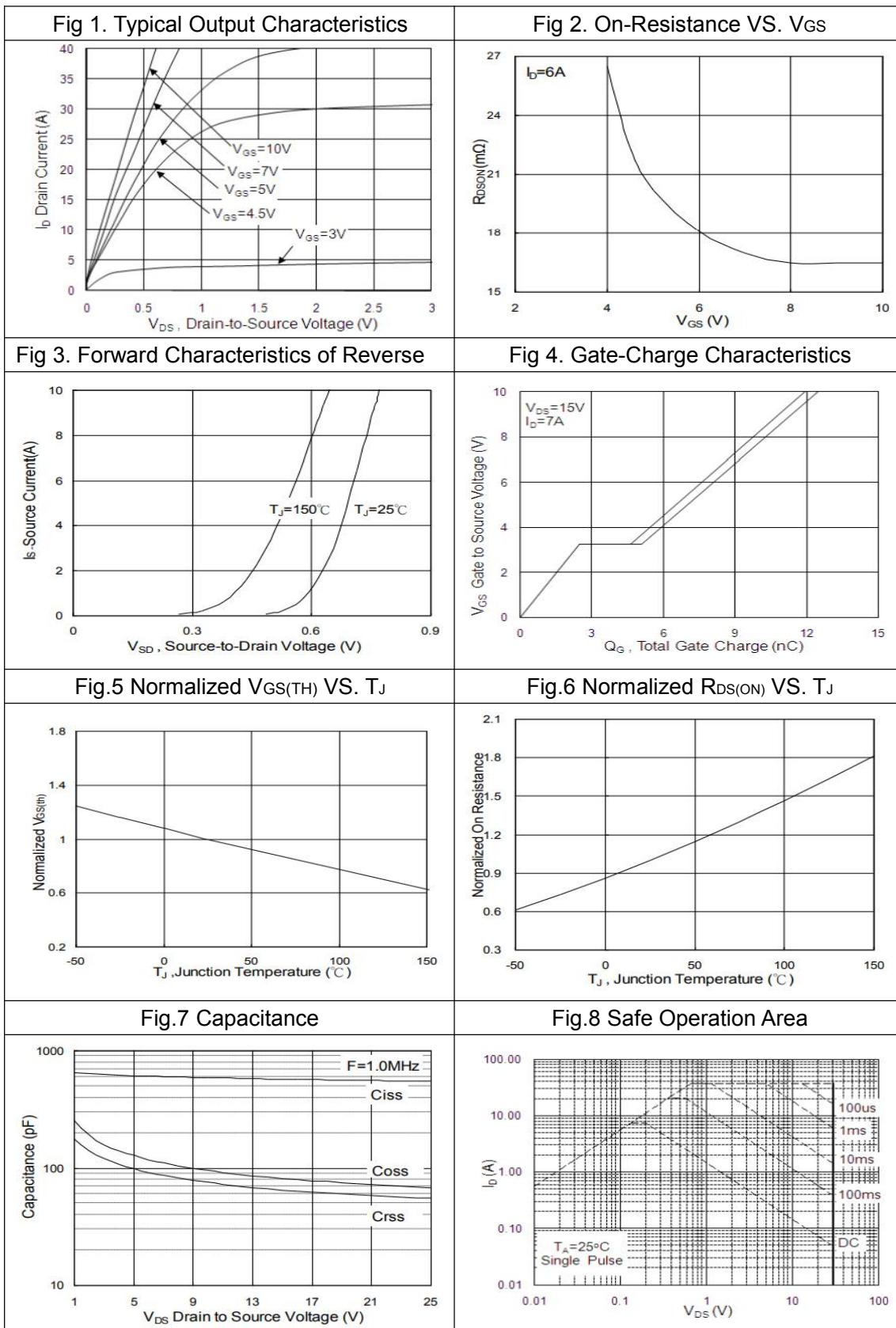
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX	Units
Drain-Source Breakdown Voltage	BVDSS	VGS=0V, ID=250uA	30			V
Zero Gate Voltage Drain Current	IDSS	VDS=24V, VGS=0V TJ=25°C			1	uA
		VDS=24V, VGS=0V TJ=55°C			5	uA
Gate Leakage Current	IGSS	VGS=±20V, VDS=0V			±100	nA
Gate threshold voltage	VGS(TH)	VDS=VGS, ID=250μA	1.2		2.5	V
Drain to Source On-state Resistance(note 2)	RDS(ON)	VGS=10V, ID=7A		15	18	mΩ
		VGS= 4.5V, ID=4A		20	26	mΩ
Drain-Source Diode Forward Voltage	VSD	Is=1A, VGS=0V			1.2	V
Gate Resistance	Rg	VDS=0V , VGS=0V , f=1MHz			2.1	Ω
Input Capacitance	Ciss	VDS=15V , VGS=0V , f=1MHz	583			pF
Output Capacitance	Coss		77			
Reverse Transfer Capacitance	CRSS		59			
Total Gate Charge (10V)	QG	VDD=15V , VGS=4.5V , ID=7A	6			nC
Gate-Source Charge	QGS		2.2			
Gate-Drain Charge	QGD		2			
Turn-On Delay Time	TD(on)	VDD=15V, VGS=10V RG=3.3Ω, ID=7A	1.2			nS
Rise Time	Tr		40			
Turn-Off Delay Time	TD(off)		18			
Fall Time	Tf		7.2			

**DIODE CHARACTERISTICS**

Parameter	Symbol	Test Conditions	MIN	TYP	MAX	Units
Drain-Source Diode Forward Voltage	VSD	Is=1A, VGS=0V			1.2	V
Continuous Source Current <sup>1,5</sup>	Is	VG=VD=0V, Force Current			7.0	A



## TYPICAL CHARACTERISTICS



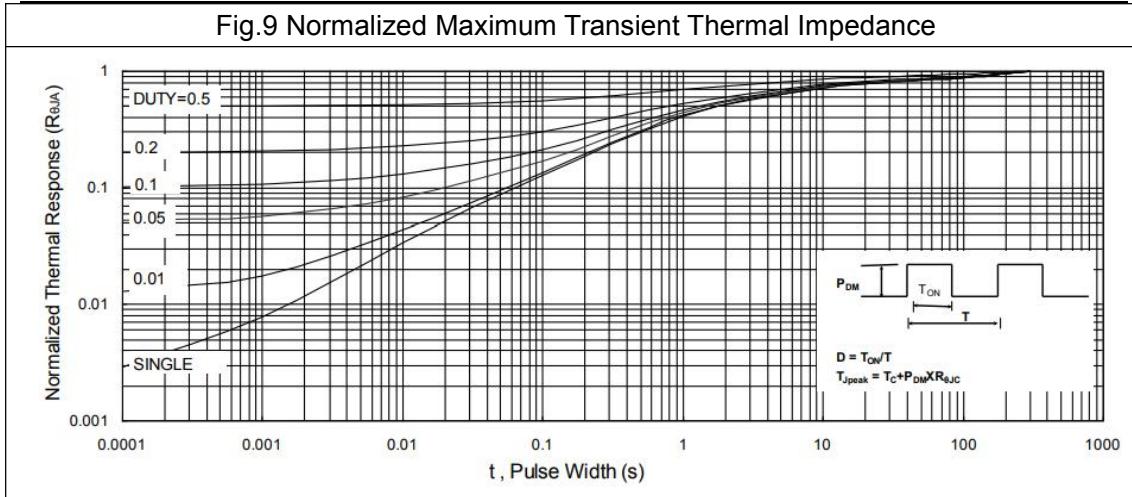


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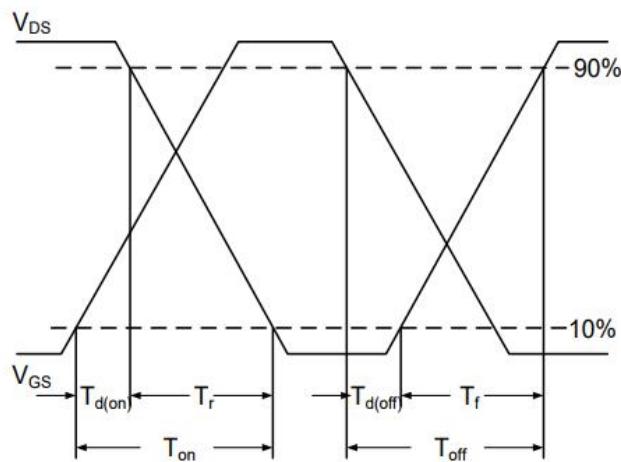
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Fig.9 Normalized Maximum Transient Thermal Impedance

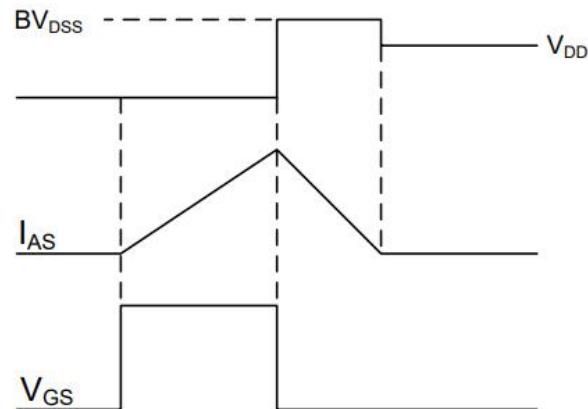


### Switching Time Waveform



### Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$





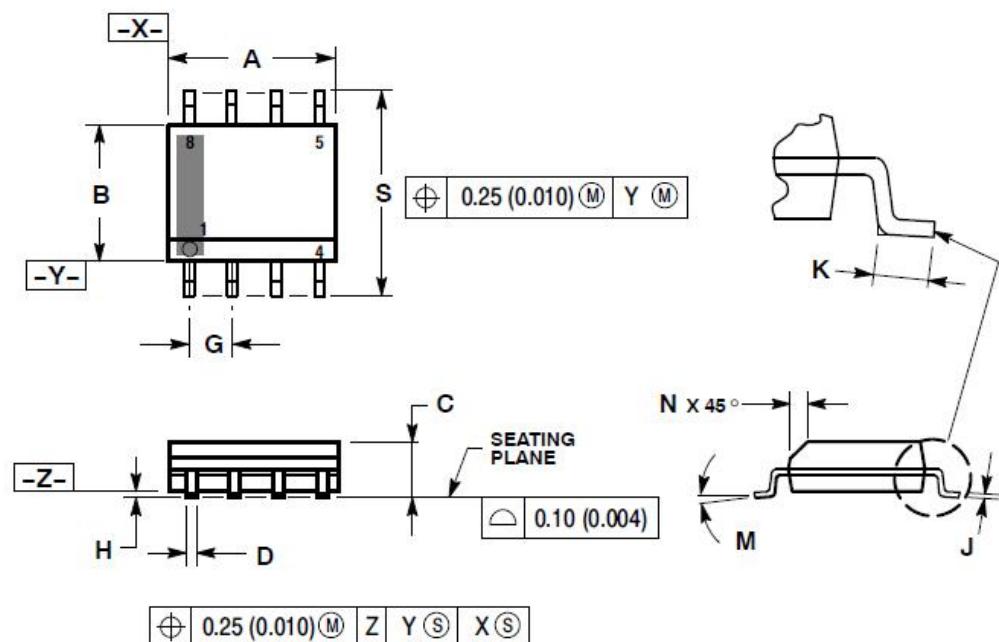
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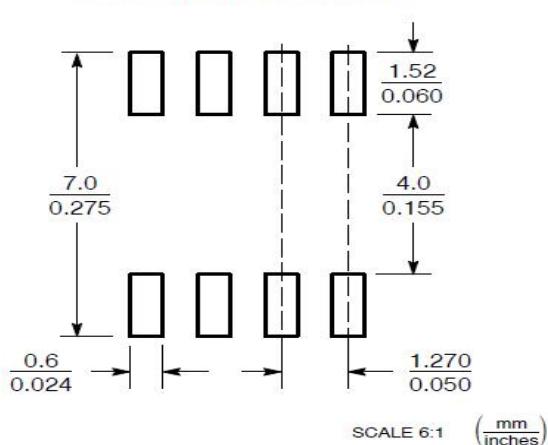
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## PACKAGE DIMENSIONS

SOP-8



### SOLDERING FOOTPRINT\*



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244